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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Docket No.: TIS-25912

Fung Leng Chen, et al.

Examiner: Not Assigned

Serial No.:

09/115,444

Art Unit:

2835

Filed: 7/14/98

High Density Internal Ball Grid Array Integrated Circuit Package

## **REQUEST FOR EXTENSION OF TIME**

Massistant Commissioner for Patents Washington, D.C. 20231

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

Tipa Rendon

11-6-98

Pursuant to 37 CFR § 1.136(a), Applicants respectfully petition the Commissioner for an extension of the shortened statutory period for response in the above-identified Application.

The fee for this extension is indicated below:

- <u>X</u> First Month (\$110)
- \_\_\_ Second Month (\$400)
- \_\_\_ Third Month (\$950)
- \_\_\_ Four Months (\$1,510)
- \_\_\_ Five Months (\$2,060)

Please charge the fee to deposit account No. 20-0668. The Commissioner is hereby authorized to charge any fees which may be required, or credit any overpayment to Account No. 20-0668. An original and two copies of this sheet are enclosed.

Texas Instruments Incorporated P.O. Box 655474, M/S 3999 Dallas, TX 75265 (972) 917-5632

(972) 917-4418

Respectfully submitted,

Mark E. Courtney Attorney for Applicants Registration No. 36,491

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